



Product Change Notification

Change Notification #: 116896 - 02
Change Title: Humidity Indicator Card (HIC),
PCN 116896-02, Transport Media,
Adding Additional Desiccant Pouch for **Half
stack and Full stack** Tray and **13” & 14”**
Tape & Reel Packed Products & Relocating
HIC placement
**Reason for Revision: Providing additional
clarification on the change**

Date of Publication: June 17, 2019

Key Characteristics of the Change:

Transport Media

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	May 22, 2019
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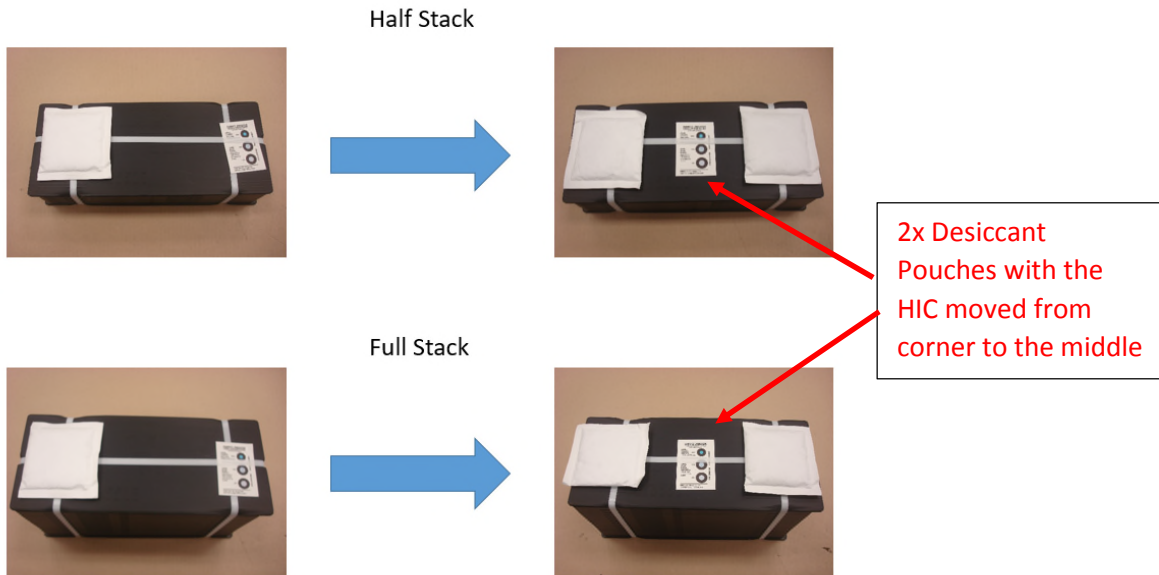
Description of Change to the Customer:

Reason for Revision: Providing additional clarification on the change

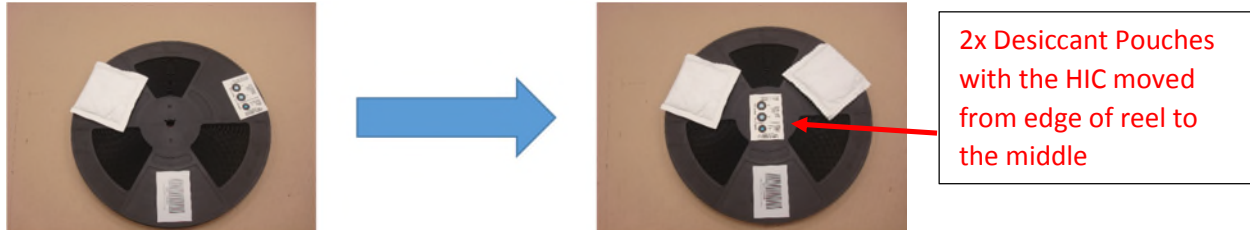
In order to address the marginality of coloration displayed on the Humidity Indicator Card (HIC) of desiccant packed products, Intel will be adding an additional desiccant pouch. The additional desiccant pouch is for Ball Grid Array (BGA) applying to Tray packed product that are shipped in either a Half-Height Intermediate Box (ie Half Stack) or a Full Intermediate Box (ie Full Stack) as well as **13” and 14”** Tape & Reel packed products. Intel Small I-box pack, Tube Pack and 7” Tape & Reel pack are not included in this change and will remain at one desiccant pouch.

As a result of adding the new desiccant pouch, the placement of the HIC will be moved to a new location. For Tray stacks, the **HIC** will be placed in the middle, while for **13” and 14”** Tape & Reels the HIC will placed in the middle of the Reel. (Pictures below are for example only)

TRAY PACKED



TAPE & REEL PACKED



Additional Note: If any product is opened within 10 days of the seal date shown on the label and the HIC is Pink (Not passing) inspect the MBB for punctures, holes and verify the seal. If these are passing then the product is safe to use.

Customer Impact of Change and Recommended Action:

There is no change to the form, fit, or function of the product due to this change. Customers should, however, notify those at the customer site who open up packaged materials to ensure they are aware of the change.

Intel will deplete older packaged material currently on shelves containing only the single desiccant pouch during the transition and therefore customers should expect to see a mix of packaging options until older packaged material has been depleted.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

The change will apply to all BGA desiccant Tray and Tape & Reel packed parts. In short, if products today are BGA products being shipped in Tray media in either a full intermediate box or a half-height box and include a desiccant pouch or Tape & Reel with a desiccant pouch, customers will now see the use of two desiccant pouches instead of one, with the HIC placed in the middle.

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
April 22, 2019	00	Originally Published PCN
June 7, 2019	01	Providing additional clarification regarding the change
June 17, 2019	02	Providing additional clarification on the change



Product Change Notification

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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